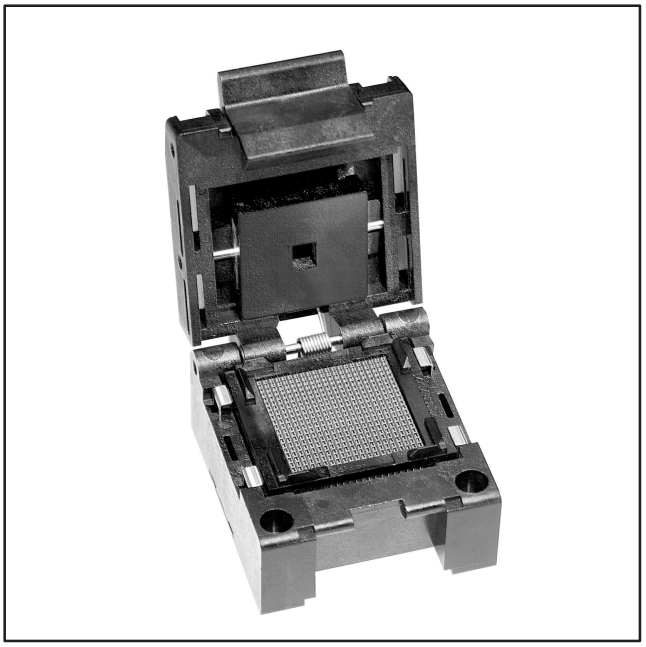
3M Textool, 1.0mm pitch, Lidded, BGA Test & Burn-In Sockets

Type I, II, III



34

- Highly reliable contact that allows for normal variation in BGA ball-diameter and position.
- Low spring-rate design achieves minimal solder ball deformation while allowing up to a 0.2mm range in package thickness tolerance
- In BGA applications, direction of contact force is at 45 deg angles away from ball-seat. Results: No ball-deformation at seating plane.
- Eliminates the problem of "hinge-pinch" while applying zero closing force.

Type	Device Size	Matrix
I	23mm Square	21 x 21
II	40mm Square	39 x 39
III	47.5mm Square	45 x 45

Date Issued: June 20, 2001

Physical

Body:
Material: Polyethersulfone (PES)
Flammability: UL 94V-0
Color: Black
Alignment Plate:
Material: Liquid Crystal Polymer (LCP)
Flammability: UL 94V-0
Color: Black
Contact:
Material: Beryllium Copper
Plating: 30 µ" (0.76 µm) Gold over 50 µ" (1.3 µm) Nickel
Other Metal Parts: **Stainless Steel**
Marking: **3M Logo / Textool Logo**

Electrical

Insulation Resistance: >1000MΩ at 500 Vdc
Dielectric Withstanding Voltage: 500 Vrms at Sea Level
Initial Contact Resistance: <100mΩ measured at 1.0 mA applied current
Current Rating: 1.0 A max @ 25° C

Environmental

Operating Temperature Rating: - 55° C to + 150° C

Mechanical

Durability: 10,000 actuations at room temperature.
Initial Contact Force: 36 gf (0.35N) Nominal
Mechanical Advantage of Lid: Type I, 2:1
Type II, 10:1
Type III, 8:1

3M Electronic Handling and Protection Division
6801 River Place Blvd.
Austin, TX 78726-9000

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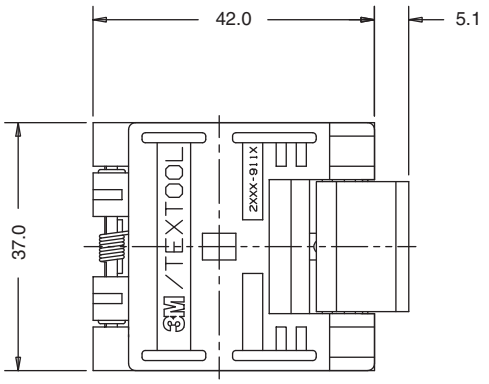
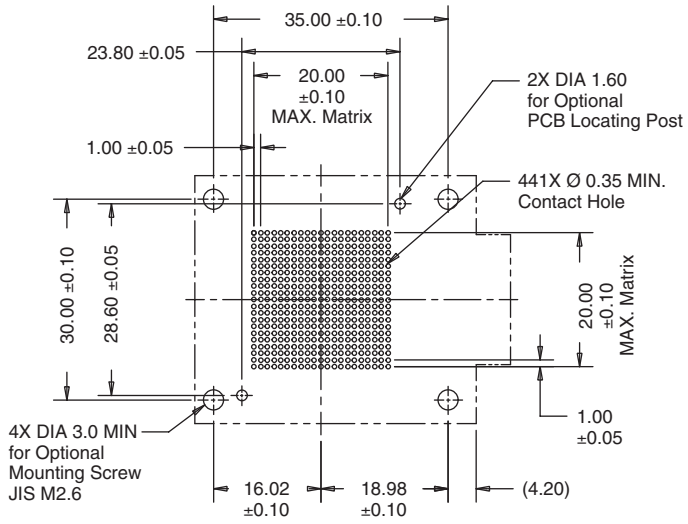
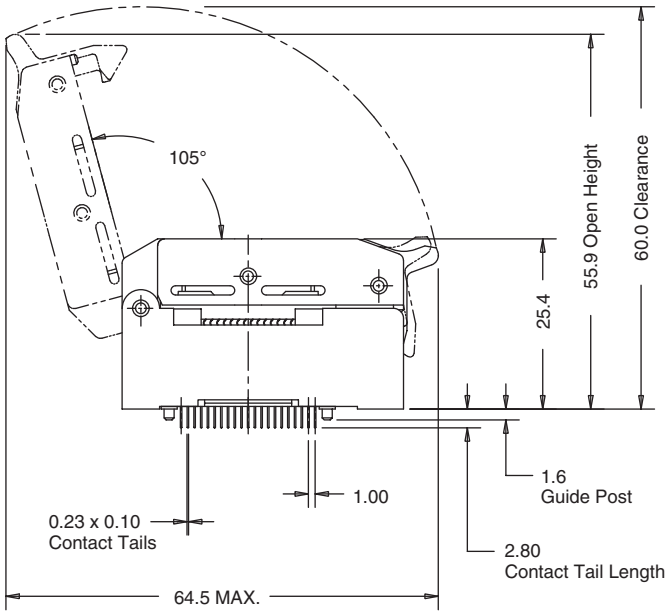
Type I





P.C. BOARD PATTERN



DIMENSIONS IN MILLIMETERS		
DIM	.0	.00
TOL	± 0.25	± 0.13

Ordering Information

PACKAGE SPECIFICATIONS	
Max Package Size	23 mm ± 0.20 mm SQ
Max Package Thickness	3.50 ± 0.10 mm
Max Matrix	21X21
Ball or Land Diameter	Dia 0.50 - 0.70 mm
Ball Height	0.40 to 0.60 mm

P.C.B. RECOMMENDATIONS	
Board Thickness	1.60 mm
Through Hole Diameter	Dia 0.35 mm Min

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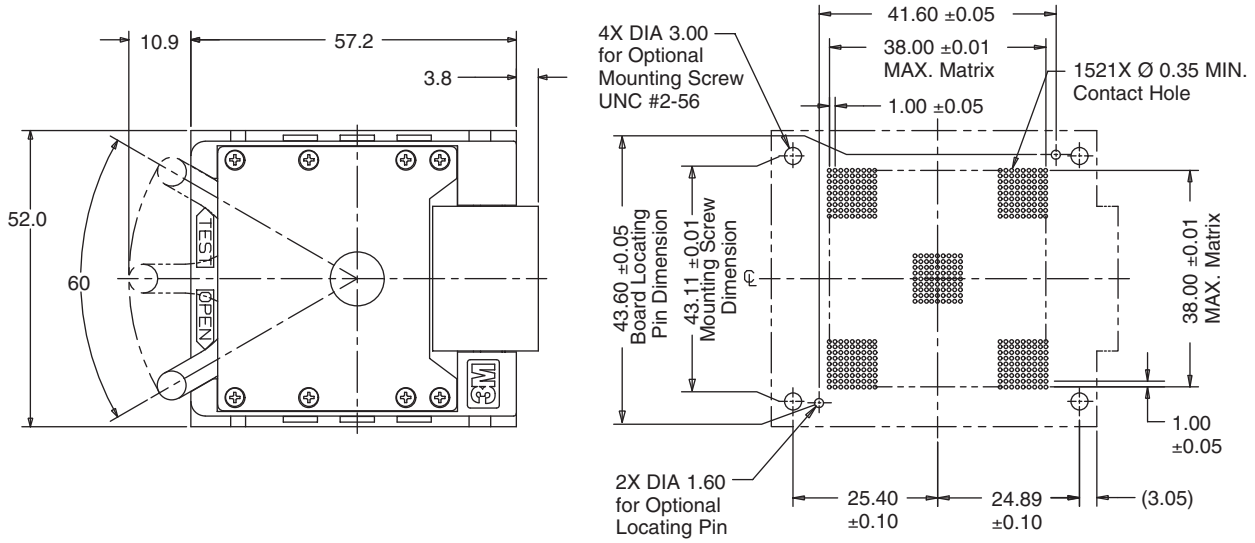
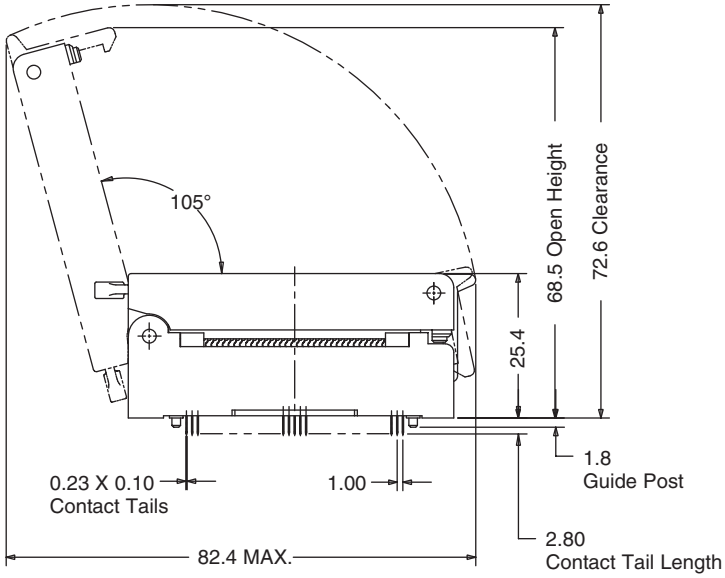
Type II



P.C. BOARD PATTERN



DIMENSIONS IN MILLIMETERS		
DIM	.0	.00
TOL	± 0.25	± 0.13

Ordering Information

PACKAGE SPECIFICATIONS	
Max Package Size	40 mm ± 0.20 mm SQ
Max Package Thickness	3.50 ± 0.10 mm
Max Matrix	39X39
Ball or Land Diameter	Dia 0.50 - 0.70 mm
Ball Height	0.40 to 0.60 mm

P.C.B. RECOMMENDATIONS	
Board Thickness	1.60 mm
Through Hole Diameter	Dia 0.35 mm Min

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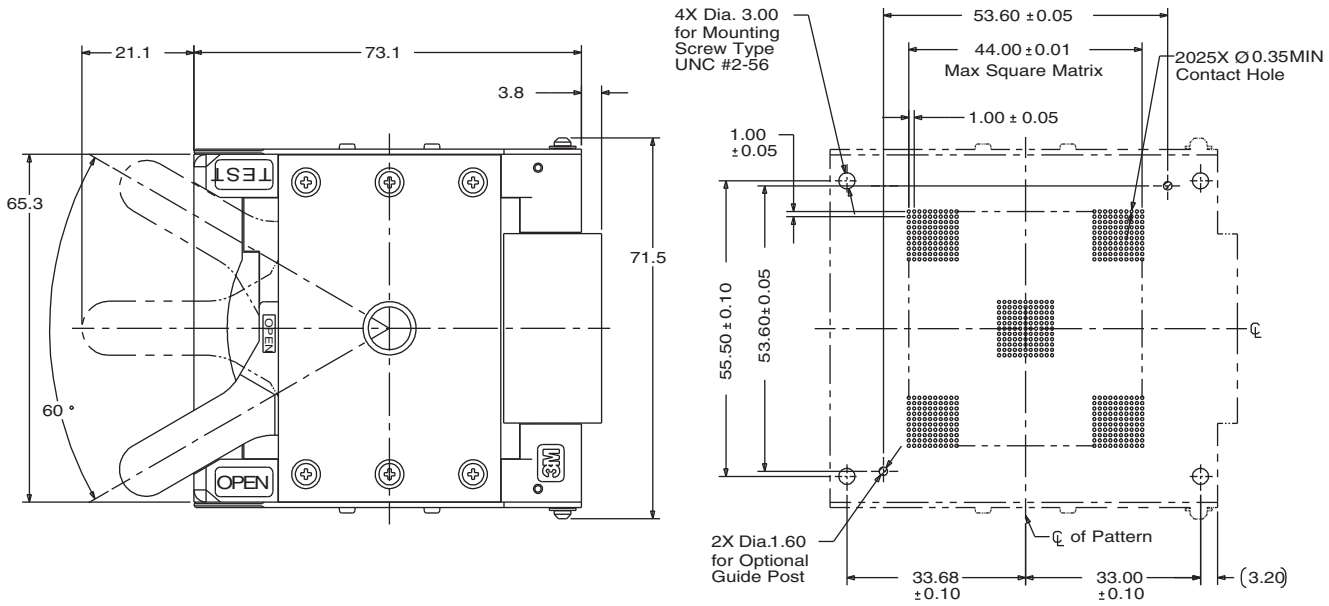
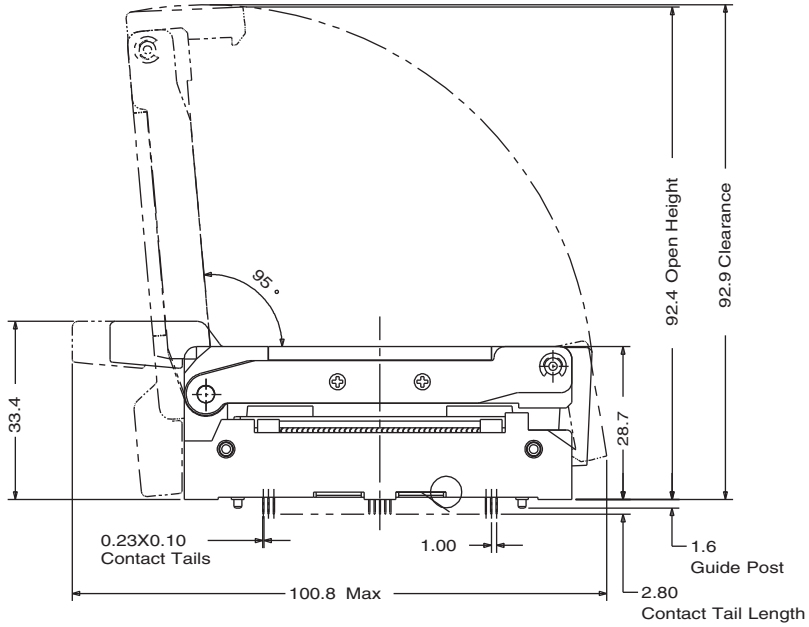
Type III



P.C. BOARD PATTERN



DIMENSIONS IN MILLIMETERS		
DIM	.0	.00
TOL	±0.25	±0.13

Ordering Information

PACKAGE SPECIFICATIONS	
Max Package Size	47.5 mm ± 0.20 mm SQ
Max Package Thickness	4.0 ± 0.10mm
Max Matrix	45 X 45
Ball or Land Diameter	0.50 to 0.70 mm
Ball Height	0.40 to 0.60 mm

P.C.B. RECOMMENDATIONS	
Board Thickness	1.60 mm
Through Hole Diameter	0.35 mm MIN

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